

FEBRUARY, 2024



Investor Presentation

Warburg Warsaw Conference

February 20, 2024

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.



SUSS MicroTec at a glance



- Hidden champion headquartered in Germany with 70+ year track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: more than € 400 million revenue and >15% EBIT margin

299

in € million

Sales 2022

446

in € million

Order intake 2022

11%

EBIT margin 2022

SUSS is part of our digital life!

Management Board of SÜSS MicroTec SE



CFO

Dr. Cornelia Ballwiesser

- Finance and Controlling
- Legal and Compliance
- Internal Audit
- Investor Relations
- IT
- ESG



CEO

Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Business Units:
Advanced Backend Solutions,
Photomask Solutions, MicroOptics



COO

Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

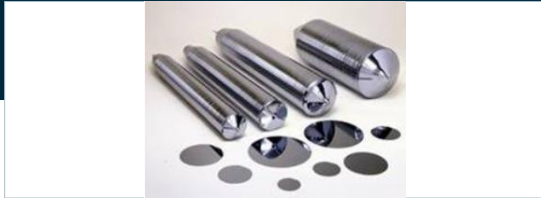
Our corporate vision defines our strategies

SUSS MicroTec Vision

**Leader in enabling innovative
advanced backend & photomask
solutions.**

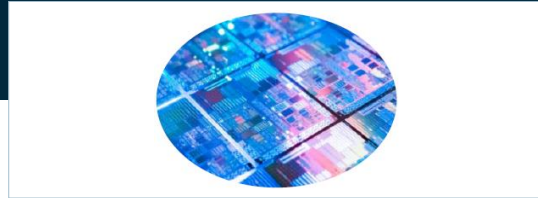
Our world are the semiconductor frontend and backend process steps

Wafer fabrication



Front-end-of-line

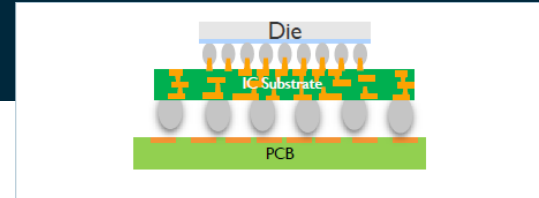
Wafer process



- Deposition/coating
- Cleaning
- **Patterning/lithography**¹
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

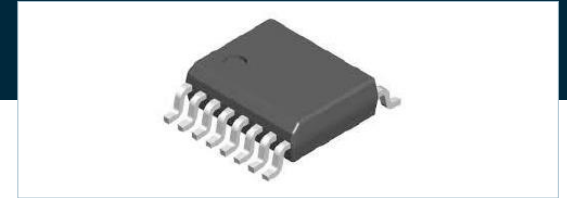
From middle-of-line to back-end-of-line

Advanced packaging



- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer-level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

¹ Only related to Photomask processing

Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Advanced Backend Solutions is the core asset in our product portfolio



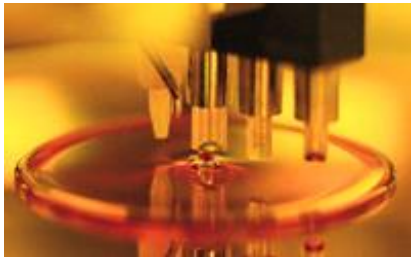
Frontend

Segments Photomask Solutions



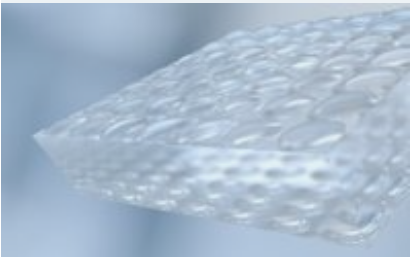
Advanced Backend

Advanced Backend Solutions



Components¹

MicroOptics



Products

Photomask Equipment



MaskTrack X

Imaging

Mask Aligner
MA200/300



Projection
Scanner
DSC300



Coating



ACS300

Bonding

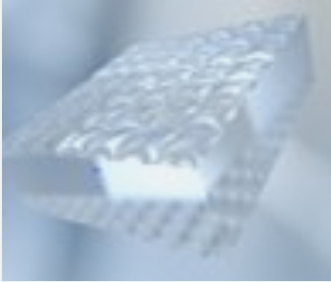
XBC300



XB8



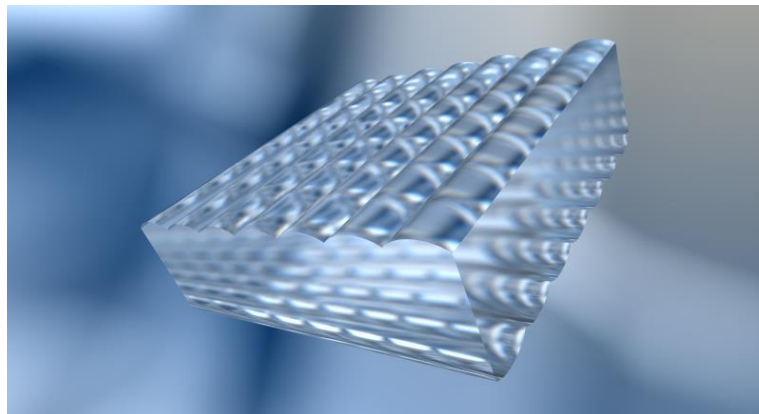
MicroLens Arrays



MicroLens Arrays

1) We completed the divestment of the MicroOptics to Focuslight Technologies in January 2024.

Divestment of MicroOptics business unit completed



1

Reasons for divestment

- Limited synergies with core semiconductor equipment businesses (R&D, manufacturing, distribution)
- Further growth requires higher investment in automation and scaling
- We do not consider ourselves to be experts in targeted automotive business

2

Key facts of transaction

- Type: share deal (acquisition of 100% of SÜSS MicroOptics SA shares)
- Transaction volume: ~ € 75 million (includes acquisition of all shares and redemption of debt)
- Signing: 8 November 2023
- Closing: 15 January 2024
- Expected extraordinary income before taxes: € 40 to 45 million

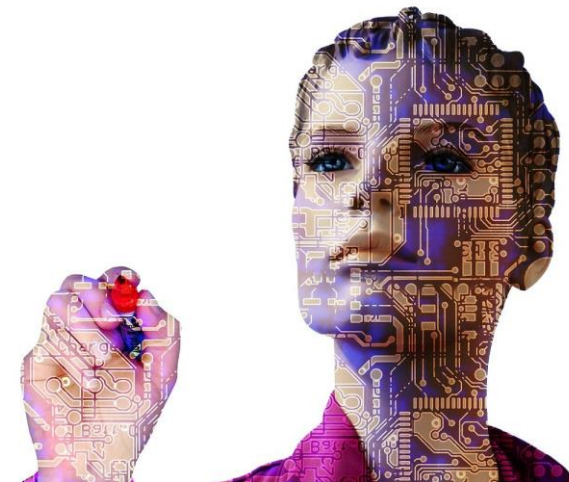
3

Buyer's profile: Focuslight

- Listed at Shanghai stock exchange (ISIN: CNE100005XV2)
- ~ 800 employees
- Focus: diode laser components and laser optics
- Experienced in Western Europe through acquisition of German based company LIMO in 2017

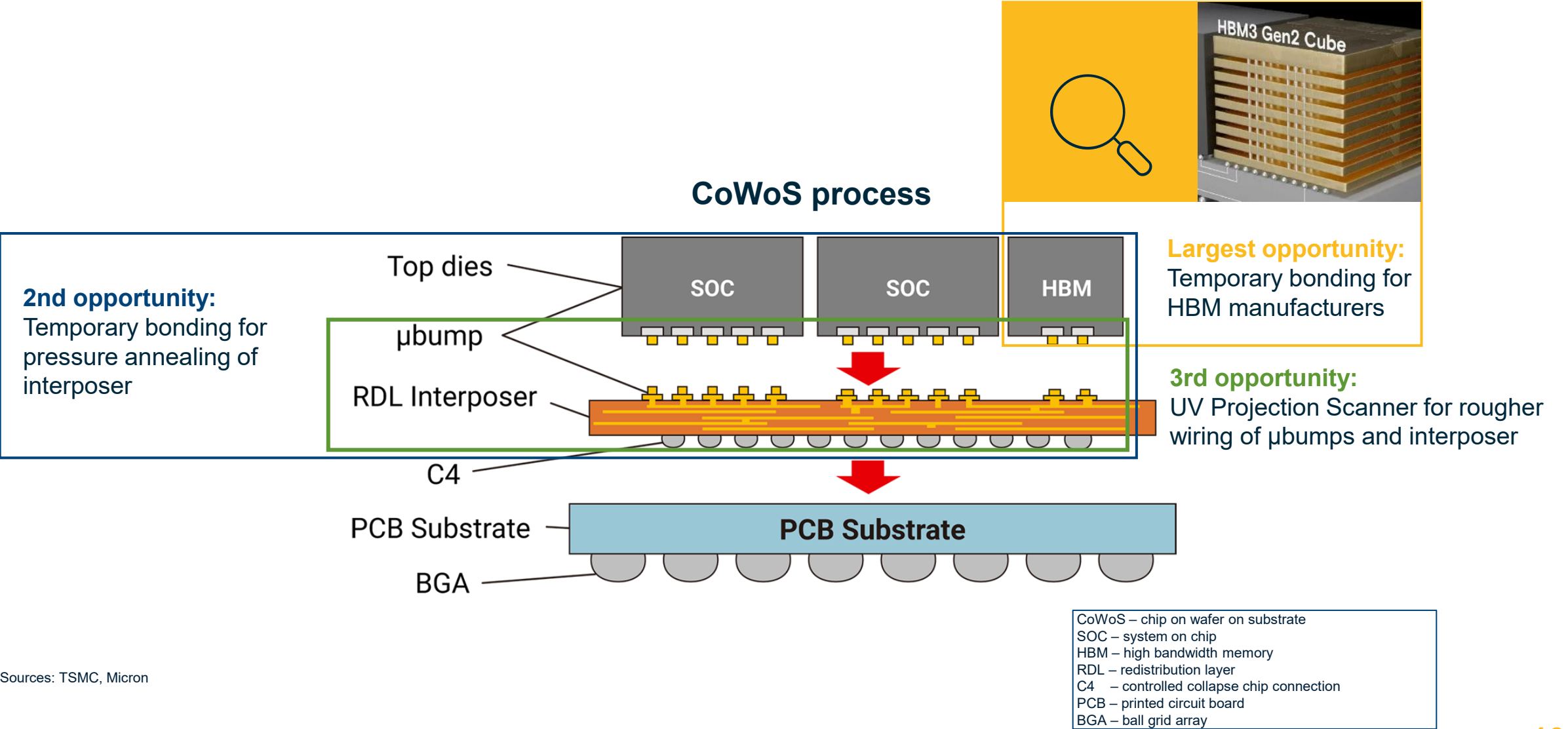
AI related opportunity is larger than we initially expected

So far, we received AI related orders for our temporary bonders, debonders and cleaners worth ~ € **100** million.



- + Demand for our solutions is boosted in particular by dramatic capacity increase at Korean and Taiwanese HBM (high bandwidth memory chip) manufacturers.
- + After a first order in June 2023, we received the largest POs in September and October.
- + As a result, we achieved the bonder's highest ever order intake in the third quarter of 2023.
- + To meet demand, we are qualifying our production site in Hsinchu (Taiwan) to build the XBS300 temporary bonding platform in the future. For this, we are hiring > 50 new employees.

We benefit from the boom in AI



Sources: TSMC, Micron

Robust order momentum remains, sales deprived by export delays

Financial Results

Q3 2023*

281.2
in € million

Order Entry
9M 2023

202.3
in € million

Sales
9M 2023

33.5
in %

Gross profit margin
9M 2023

6.3
in %

EBIT Margin
9M 2023

**Guidance adjustment on October 25, 2023
for all three key financial indicators**

*excluding SUSS MicroOptics

Solid order entry exceeded market expectations

In € million	9M 2023	9M 2022	Change
Order intake	281.2	345.5	-18.6%
Order backlog as of September 30	414.7	363.2	14.2%
Sales	202.3	166.1	21.8%
Gross profit	67.7	60.2	12.5%
Gross profit margin	33.5%	36.2%	-2.8%-pts
EBIT	12.8	8.8	45.5%
EBIT margin	6.3%	5.3%	1.0%-pts
Earnings after tax	9.8	5.1	92.2%
Earnings per share, basic (in €)	0.51	0.27	88.9%
Net cash	32.7	41.3	-20.8%
Free Cashflow	0.1	28.3	-99.6%
Employees as of September 30	1,133	1,058	7.1%

- **Good order intake and very high order backlog** remain a solid foundation for growth in Q4 2023 and beyond (despite the adjustment of the 2023 sales target)
- **Absolute gross profit and EBIT increased yoy**
- **Gross profit margin and EBIT margin not in line with expectations**, mainly because of China related shipment delays, an unfavorable product mix and increased outsourcing activities
- Company has nevertheless created **value for shareholders** in 9M 2023 (earnings per share +88.9%)
- **Net cash position decreased** due to further built up of inventories

Division Overview 9M 2023

Advanced Backend Solutions

in € million	9M 2023	9M 2022
Order intake	187.1	229.3
- thereof Lithography	103.6	163.3
- thereof Bonder	83.5	66.0
Total sales¹	146.9	131.7
- thereof Lithography	106.5	105.9
- thereof Bonder	40.3	25.8
Gross profit	51.7	49.0
Gross profit margin	35.2%	37.2%
EBIT	10.2	7.7
EBIT margin	6.9%	5.9%

- Decrease in order intake yoy after very strong 9M in fiscal year 2022, but very good order situation on Bonder product lines
- Sales increased by 11.5 % yoy, mainly driven by bonder business
- Gross profit margin decreased because of lower sales with high margin tools
- EBIT margin went up from 5.9% to 6.9%, due to strong Q2 results

Photomask Solutions

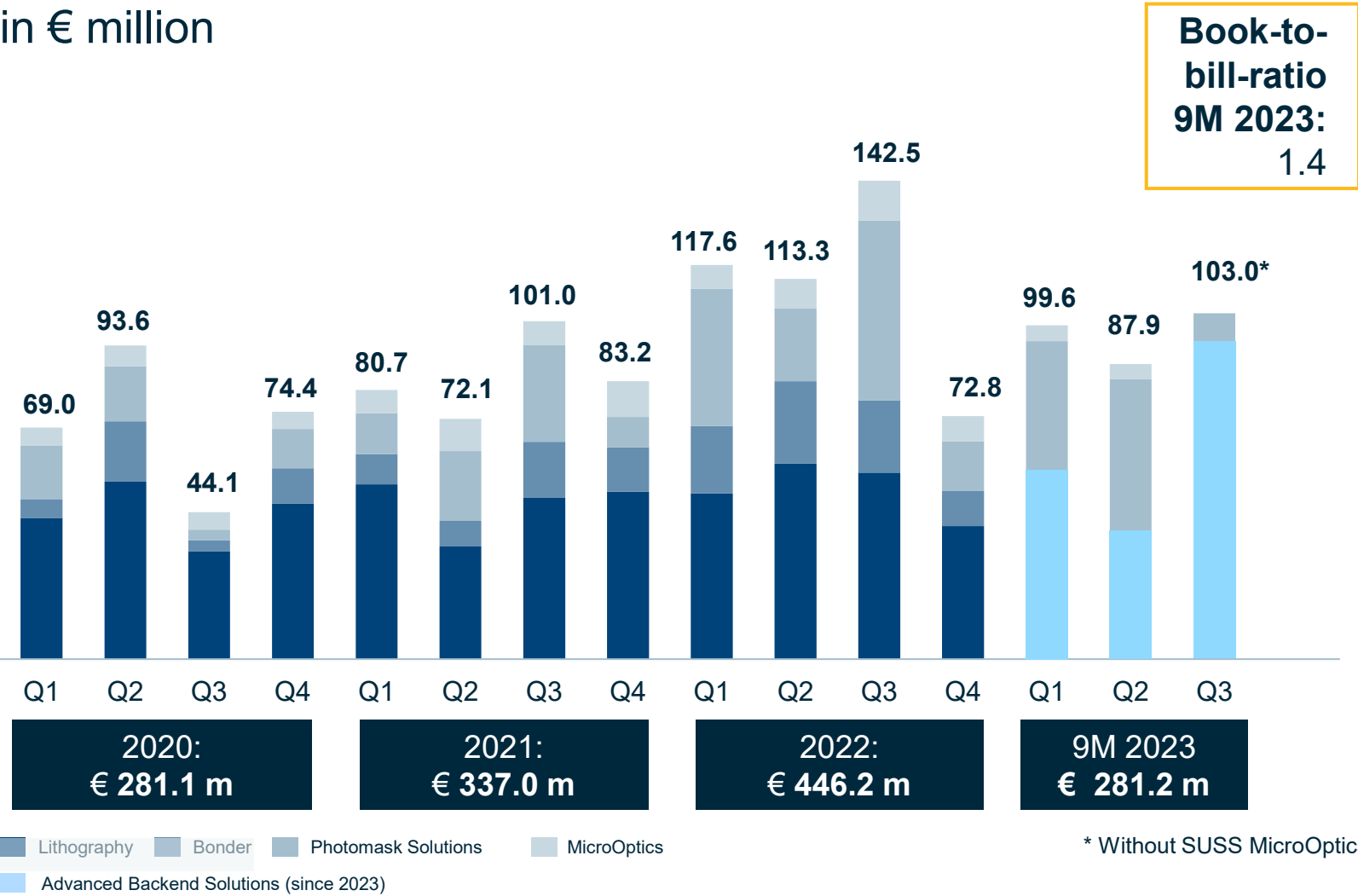
in € million	9M 2023	9M 2022
Order intake	94.1	116.2
Total sales¹	55.5	34.4
Gross profit	16.2	10.8
Gross profit margin	29.2%	31.3%
EBIT	6.2	4.7
EBIT margin	11.2%	13.7%

- Order intake decreased, but remains on a good level compared to prior years
- High order backlog (~ €170 million as of September 30) provides huge growth opportunity
- Sales benefited from high backlog and improved supply chain situation
- Absolute gross profit and EBIT improved
- Decline in gross profit margin and EBIT margin due to higher R&D costs for the development of a disruptive wafer cleaning solution

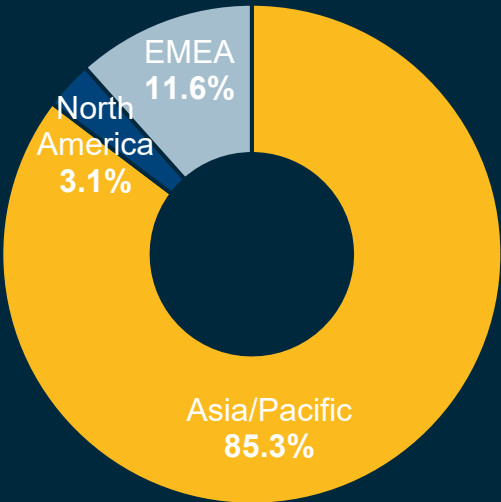
1) Total sales include internal sales (sales to other divisions) since 2021; gross profit margin and EBIT margin are calculated on the basis of total sales.

Order Intake by Division and Region

Order Intake by Division in € million



Order Intake by Region 9M 2023



Revised guidance due to delayed deliveries to China and unsatisfying margins

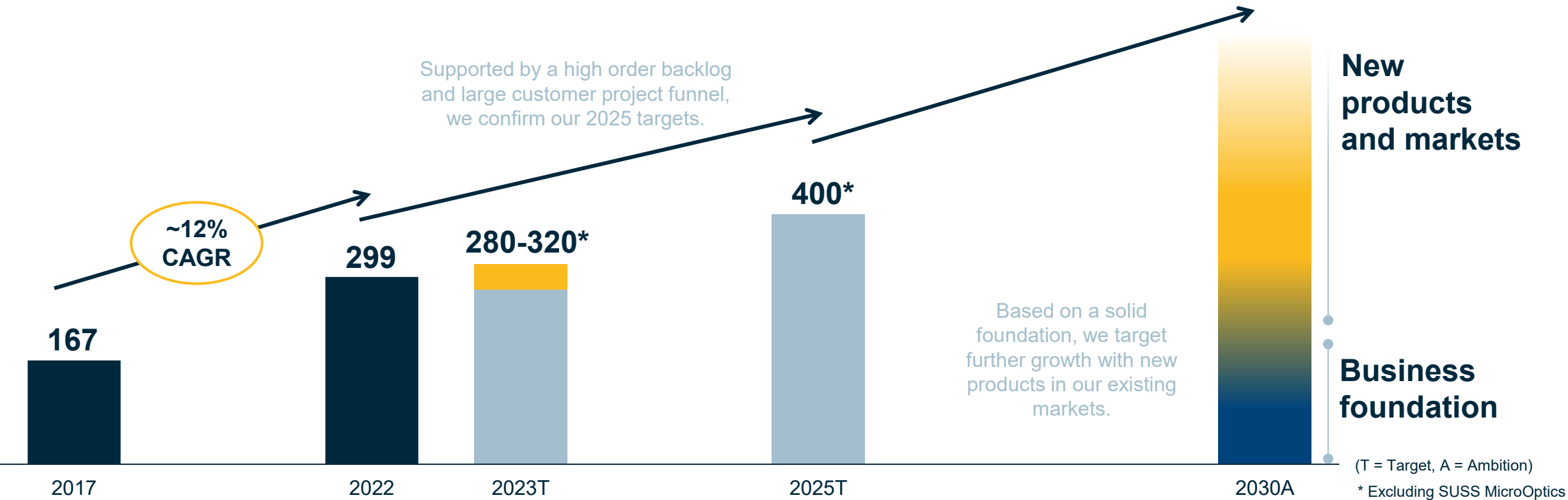
Our adjusted guidance 2023



1) Without SUSS MicroOptics

2) Including one-off effects of € 3.1 million. Operating EBIT margin thus accounted to 9.9%.

Based on our business foundation we see further potential beyond



Major growth drivers 2023

- Converting high order backlog in Photomask Solutions and Bonder business into sales growth

Major growth drivers 2024/2025

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

Investor Relations Information

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Financial Calendar 2024



March 27
Annual Report 2023



May 8
Q1 Report 2024



June 11
Annual General Meeting 2024



August 7
Half Year Report 2024



November 7
Nine Months Report 2024